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Remarks

Claims 1-42 remain in the application. Claims 7, 10, 12, 14-16, and 19-32 have been withdrawn from consideration.

The allowance of claims 33-42 is noted.

By the amendment, claim 1 has been amended to more particularly set-out applicants' invention. Original claims 2 and 3 support the changes to claim 1. Additionally, claims 2 and 3 have been amended. The specification at paragraph [0027] supports the changes to claims 2 and 3.

In addition, the specification has been amended to correct an inadvertent paragraph numbering error. Also, paragraphs [0004] and [0019] have been amended to correct minor typographical errors, and paragraph [0026] has been amended to include a "." at the end of the paragraph.

Response to First 35 U.S.C. §102 Rejection

Claims 1, 3-5, 8, 11, 13, 17, and 18 were rejected under 35 U.S.C. §102(e) as being anticipated by Sakamoto et al., USP 6,624,511, (hereinafter "Sakamoto"). This rejection is respectfully traversed in view of the amendments made herein and the remarks presented hereinafter.

Claim 1 calls for an electronic device package comprising a support substrate including a flag, wherein the flag has a bonding surface. A first electronic chip having a first peripheral edge is attached to a first portion of the bonding surface with a first die attach material. A first continuous trench is formed in the flag in proximity to the first peripheral edge, wherein the first continuous trench includes a continuously rounded cross-sectional shape and an inner edge adjacent to the first peripheral edge, and wherein the first continuous trench

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surrounds the first electronic chip. An encapsulant covers the first electronic chip and at least a portion of the curved sidewall surface.

Applicants respectfully submit that Sakamoto fails to anticipate claim 1 because Sakamoto does not show a first continuous trench that surrounds a first electronic chip as called for in claim 1.

Claims 3-5, 8, 11, 13, 17, and 18 depend from claim 1 and are believed allowable for at least the same reason as claim 1.

Response to Second 35 U.S.C. §102 Rejection

Claims 1-3, 5, 8, 13, 17 and 18 were rejected under 35 U.S.C. 102(e) as being anticipated by Hasebe et al., USP 6,713,849 (hereinafter "Hasebe"). This rejection is respectfully traversed in view of the amendments made herein and the remarks presented hereinafter.

Claim 1 calls for an electronic device package comprising a support substrate including a flag, wherein the flag has a bonding surface. A first electronic chip having a first peripheral edge is attached to a first portion of the bonding surface with a first die attach material. A first continuous trench is formed in the flag in proximity to the first peripheral edge, wherein the first continuous trench includes a continuously rounded cross-sectional shape and an inner edge adjacent to the first peripheral edge, and wherein the first continuous trench surrounds the first electronic chip. An encapsulant covers the first electronic chip and at least a portion of the curved sidewall surface.

Applicants respectfully submit that Hasebe fails to anticipate claim 1 because Hasebe does not show a first continuous trench including a continuously rounded cross-

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sectional shape as called for in claim 1.

Claims 3, 5, 8, 13, 17, and 18 depend from claim 1 and are believed allowable for at least the same reason as claim 1.

Response to 35 U.S.C. §103 Rejection

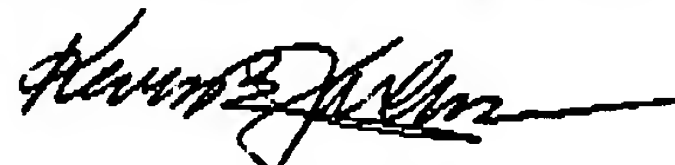
Claims 6 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Sakamoto. This rejection is respectfully traversed in view of the amendments made herein and the remarks presented hereinafter.

Claims 6 and 9 depend from claim 1. Applicants respectfully submit that claim 1 is allowable over Sakamoto because the cited reference does not show or suggest a first continuous trench that surrounds a first electronic chip as called for in claim 1. Claims 6 and 9 are believed allowable for at least this reason.

In view of all the above, it is believed that the balance of the claims are allowable, and the case is in condition for allowance, which action is earnestly solicited.

Respectfully submitted,

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